

## **Application Data Sheet**

### **Application Information**

Application Type:: Regular  
Subject Matter:: Utility  
CD-ROM or CD-R? None  
Title:: Semiconductor Package With Substrate  
Coupled To A Peripheral Side Surface Of  
A Semiconductor Die  
Attorney Docket Number:: BK-00006  
Request for Early Publication?: No  
Request for Non-Publication?: YES  
Suggested Drawing Figure:: 1A  
Total Drawing Sheets:: 14  
Small Entity:: No  
Petition included?: No  
Secrecy Order in Parent Appl.?: No

### **Applicant Information**

Applicant Authority type:: Inventor  
Primary Citizenship Country:: Republic of Korea  
Status:: Full Capacity  
Given Name:: Byong  
Middle Name:: Il  
Family Name:: Heo  
City of Residence:: Buk-gu  
Country of Residence:: Republic of Korea  
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### **Correspondence Information**

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### **Representative Information**

Representative Customer Number:: 022888

**Assignee Information**

Assignee Name::	Amkor Technology, Inc.
Street of mailing::	
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State of Province of mailing::	
address::	AZ
Country of mailing address::	US
Postal or Zip Code of mailing::	
address::	85248-1604